



### Optic Sensor Emitter

### DDL2008M

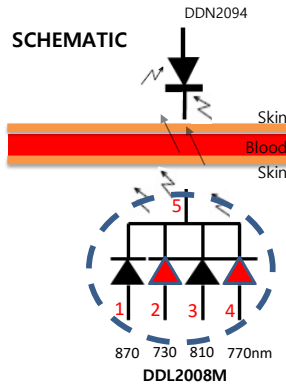
Quadruple LED Lighting

#### FEATURES

Quadruple LEDs Lighting  
Chip on Board Mold Package

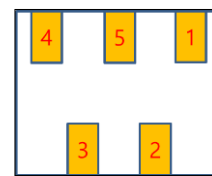
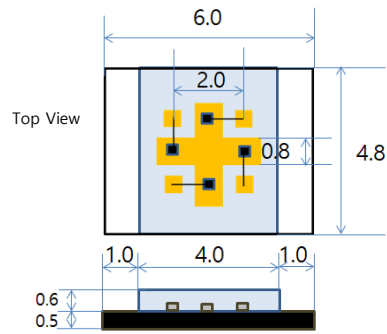
#### APPLICATIONS

Transmissive (Reflective) Emitting  
Blood Flow Analysis  
Medical Device  
Pulse Oximeter



#### PACKAGE DIMENSION (mm)

w x h x t = 6.0 x 4.8 x 1.1



#### ABSOLUTE MAX. RATINGS (Ta=25°C unless otherwise noted)

SYMBOL	PARAMETER	MAX. RATED VALUE	UNITS
PD	Power Dissipation	120	mW
IF	Continuous Forward Current	50	mA
IFP	Peak Forward Current	100	mA
VR	Reverse Voltage	5	V
T stg	Storage Temp	-20 ~ +85	°C
T opr	Operating Temp	-20 ~ +80	°C
T sd	Soldering Temperature*1	240	°C

\*Soldering time : t < 3s, \*\*Moisture Sensivity Level 3

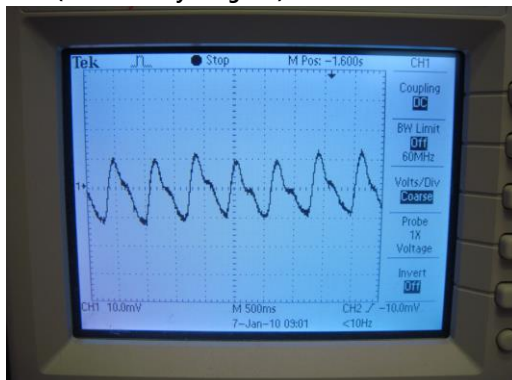
\*\*\*Do not soldering on top pads, must soldering on only backside pads

\*\*\*\*Do prebake 150°C 2HRs if reflow SMT

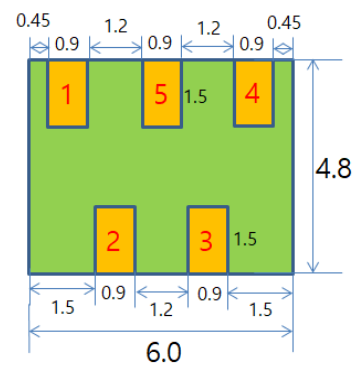
#### CHARACTERISTICS (Ta=25°C unless otherwise noted)

SYMBOL	CHARACTERISTIC	COMPONENTS	TEST CONDITION	MIN	TYP	MAX	UNITS
VF	Forward Voltage	LED1	IF=20mA		1.4	1.5	V
		LED2		1.7	1.9		
		LED3		1.5	1.6		
		LED4		1.6	1.8		
IR	Reverse Breakdown Current	LED 1, 2, 3, 4	VR=5V			10	uA
PO	Output Power	LED1	IF=20mA		5.4		mW
		LED2		4.4			
		LED3		5.1			
		LED4		3.8			
λ PEAK	Peak Wavelength	LED1	IF=20mA		870		nm
		LED2		730			
		LED3		805			
		LED4		763			
Δλ	Half Wave Width	1, 2, 3, 4	IF=20mA		50		nm

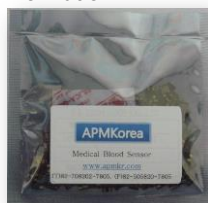
#### PPG(Photo Plethysmogram) Characteristic DDL2008M with DDN2094



#### Footprint Top View (mm)



#### Packing Information



Anti Static vinyl bag

Label sticker

Recommend Reflow Soldering Profile & Prebake 150°C 2HRs for moisture free

Soldering 235°C within 10sec  
Gradual cooling to avoid quenching

